Figure FF1-FF6 Family Performance Curves

Figure FF1

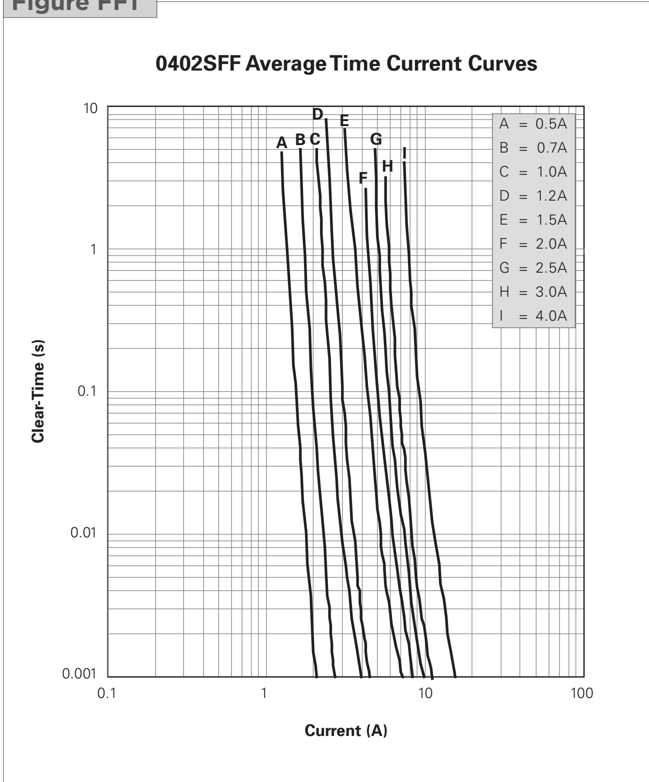
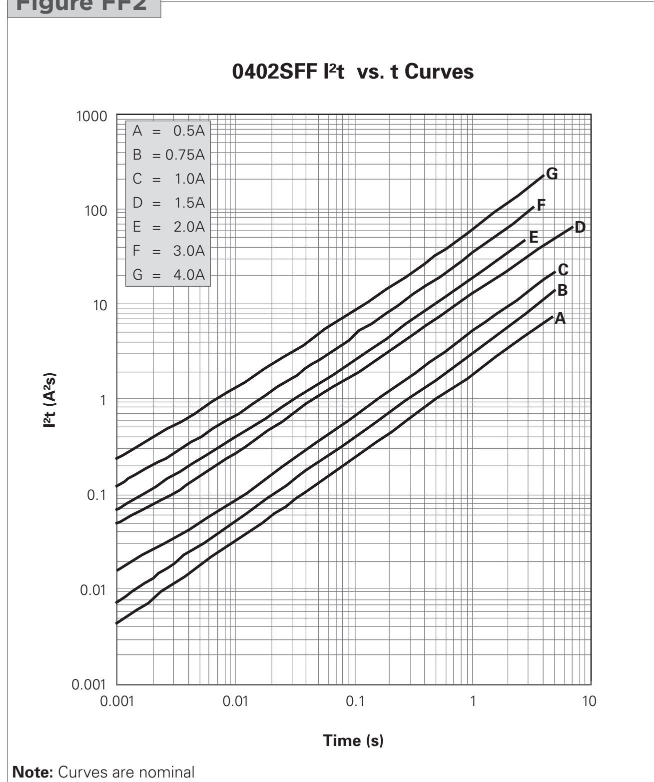


Figure FF2



Note: Curves are nominal

Figure FF3

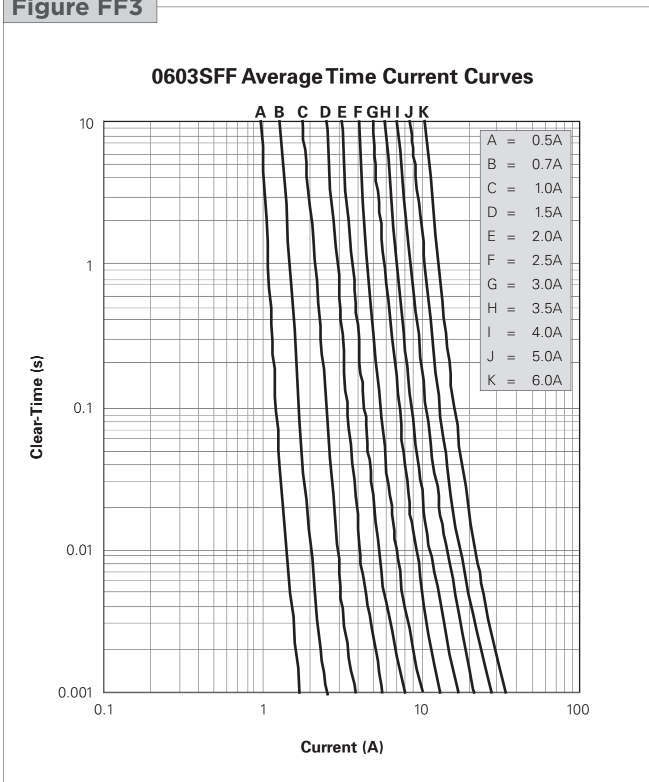
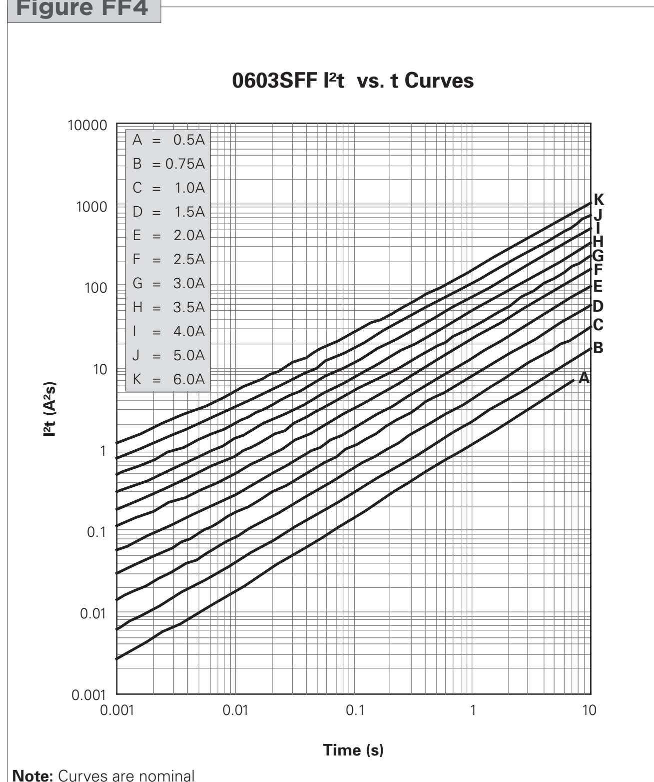


Figure FF4



Note: Curves are nominal

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Figure FF1-FF6 Family Performance Curves ... Cont'd

Figure FF5

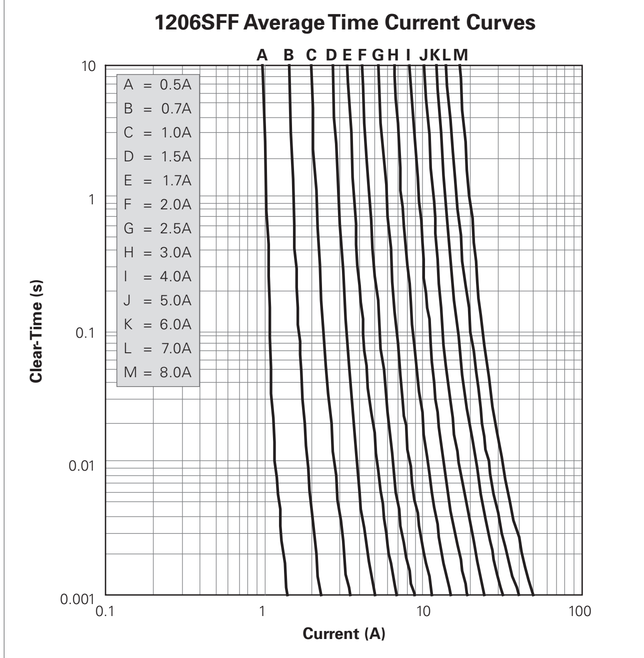
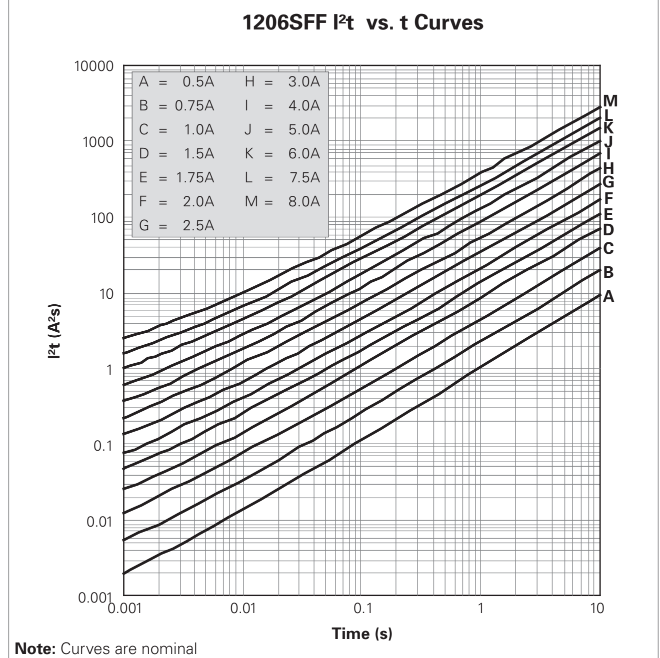


Figure FF6



Note: Curves are nominal

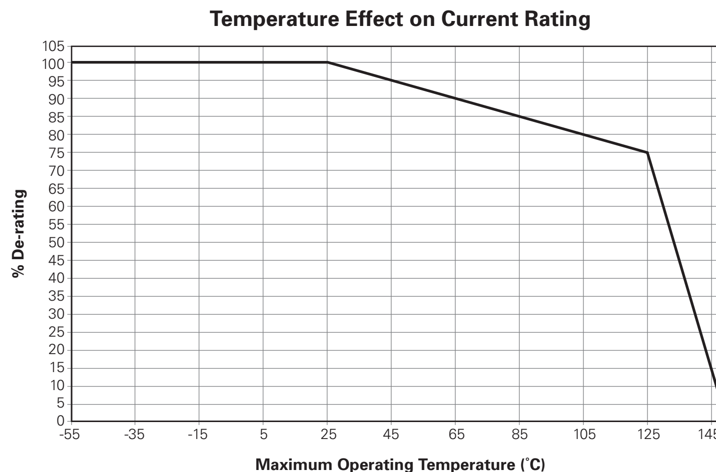
Table FF3 Environmental Specifications for Fast-Acting Chip Fuses

Operating temperature	-55°C to +125°C
Mechanical vibration	Withstands 5-3000 Hz at 30 Gs when evaluated per Method 204 of MIL-STD-202
Mechanical shock	Withstands 1500 Gs, 0.5 millisecond half-sine pulses when evaluated per Method 213 of MIL-STD-202
Thermal shock	Withstands 100 cycles from -65°C to +125°C when evaluated per Method 107 of MIL-STD-202
Resistance to soldering heat	Withstands 60 seconds at +260°C when evaluated per Method 210 of MIL-STD-202
Solderability	Meets 95% minimum coverage requirement when evaluated per Method 208 of MIL-STD-202
Moisture resistance	Withstands 10 cycles when evaluated per Method 106 of MIL-STD-202
Salt spray	Withstands 48-hour exposure when evaluated per Method 101 of MIL-STD-202

Table FF4 Material Specifications for Fast-Acting Chip Fuses

Construction body material	Ceramic
Termination material	Silver, Nickel, Tin
Fuse element	Silver

Figure FF7 Thermal Derating Current for Fast-Acting Chip Fuses



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